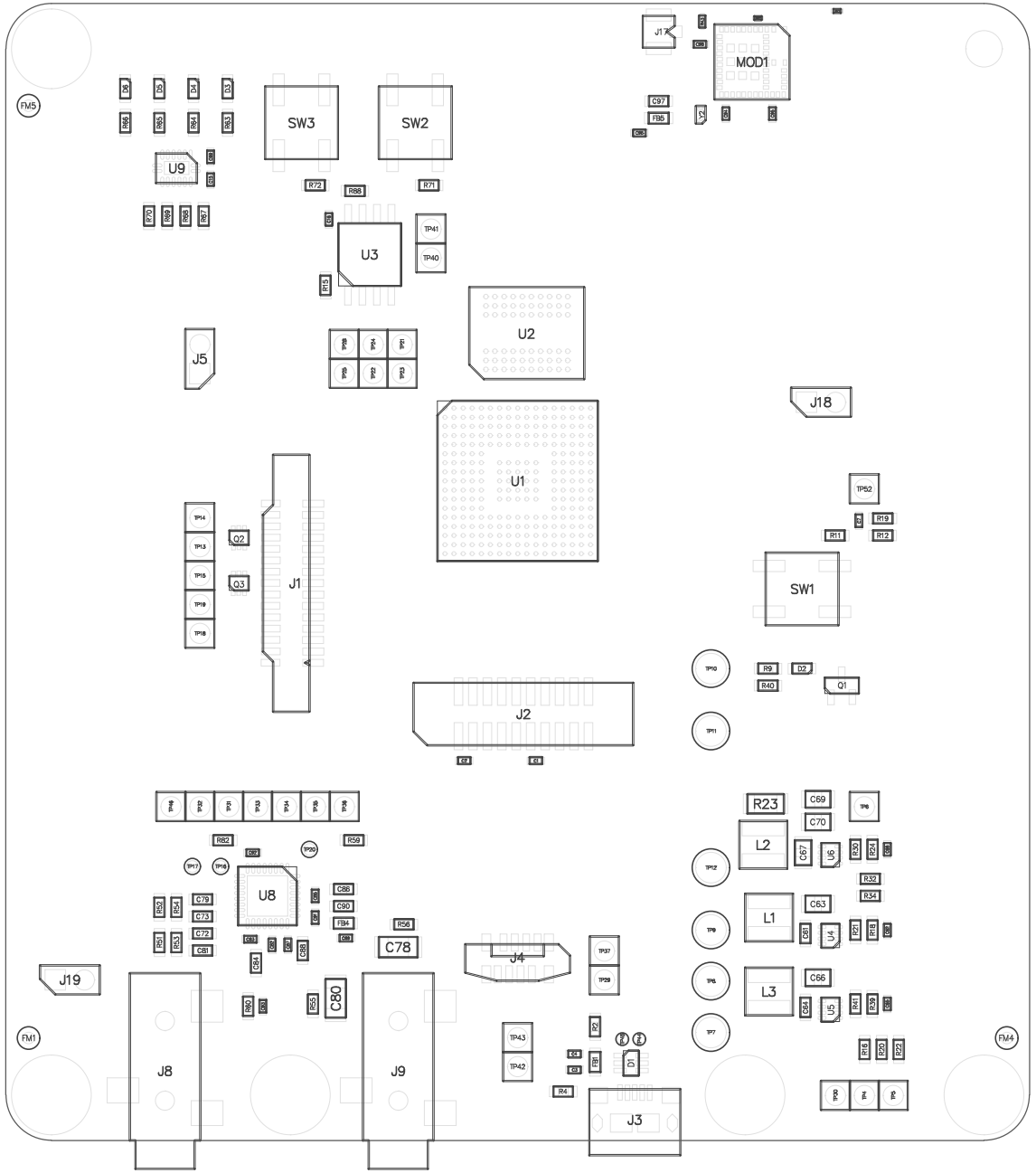
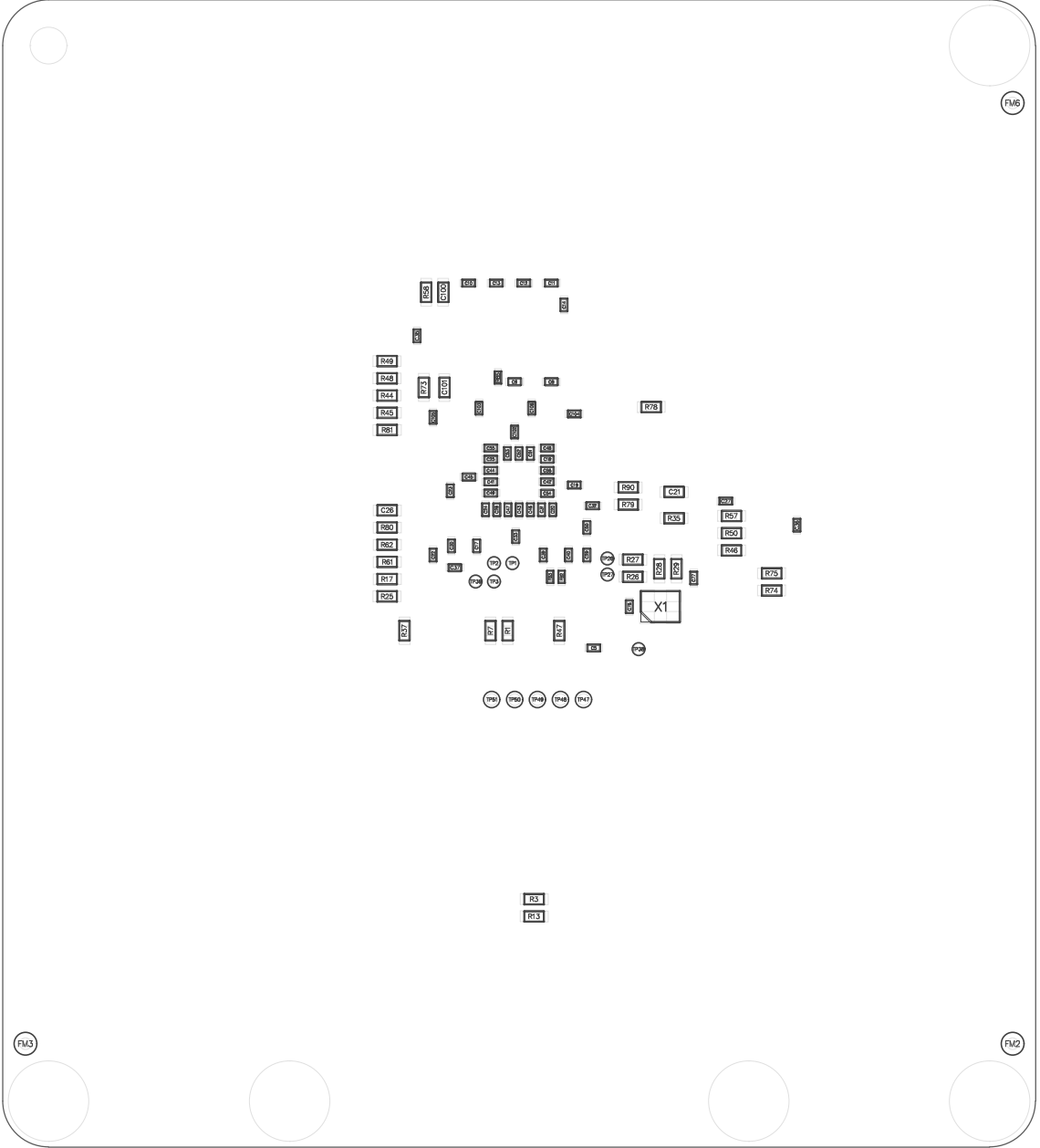


PCB ASSEMBLY INSTRUCTIONS

- 1.) SOLDERPASTE – ROHS/LEAD FREE NO CLEAN SOLDERPASTE.
PADS HAVE NOT BEEN UNDERSIZED.
ASSEMBLER SHOULD UNDERSIZE PADS TO SUIT PROCESS.
SUGGEST 125UM MAX STENCIL THICKNESS.
- 2.) ONLY COMPONENT PINS TO BE SOLDERED SHOULD BE EXPOSED TO SOLDER WAVE.
ALL OTHER EXPOSED COPPER TO BE MASKED.
- 3.) TWO PIN COMPONENT ORIENTATION:
POLARISED MOLDED CAPACITORS – PIN 1 IS THE POLARIY MARK PIN (POSITIVE).
MOLDED DIODES – PIN 1 IS THE POLARITY MARK PIN (CATHODE).
- 4.) ENSURE THROUGH HOLE PINS OF USB CONNECTOR J3 ARE SOLDERED IN ADDITION TO SMD PADS.
- 5.) NOTE THAT USB CONNECTOR J3 IS NOT FLAT SO REQUIRES A RELIEF OUTSIDE THE EDGE OF THE BOARD
- 6.) NOTE MODULE MOD1 IS AN LGA WITH SMALL PADS WHICH REQUIRES ACCURATE PASTE DEPOSITION.
SEE SILICON LABS APP NOTE AN1223–LGA–MANUFACTURING–GUIDANCE.





BOTTOM ASSEMBLY